·	Application No.		Applicant(s)	
Notice of Allowability	09/960,089 KOOPMANS, MICHEL		IEL	
	Examiner		Art Unit	
	Alonzo Chamblis	ss	2827	
The MAILING DATE of this communication app All claims being allowable, PROSECUTION ON THE MERITS IS herewith (or previously mailed), a Notice of Allowance (PTOL-85 NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT F of the Office or upon petition by the applicant. See 37 CFR 1.31	S (OR REMAINS) C i) or other appropria RIGHTS. This appli	LOSED in this appli te communication v	ication. If not includ vill be mailed in due	ed course. THIS
 This communication is responsive to <u>amendment B filed of the second of t</u>	er. nder 35 U.S.C. § 11 ve been received.			
3. Copies of the certified copies of the priority de International Bureau (PCT Rule 17.2(a)). * Certified copies not received: 5. Acknowledgment is made of a claim for domestic priority (a) The translation of the foreign language provisional 6. Acknowledgment is made of a claim for domestic priority (a)	ocuments have bee under 35 U.S.C. § 1 application has bee	n received in this na 19(e) (to a provision on received.	ational stage applica	ation from the
Applicant has THREE MONTHS FROM THE "MAILING DATE" of below. Failure to timely comply will result in ABANDONMENT of the substitution of the substi	f this application. T	THIS THREE-MONT ached EXAMINER'S	FH PERIOD IS NOT S AMENDMENT or I	EXTENDABLE
 8. CORRECTED DRAWINGS must be submitted. (a) including changes required by the Notice of Draftspe 1) hereto or 2) to Paper No (b) including changes required by the proposed drawing (c) including changes required by the attached Examine Identifying indicia such as the application number (see 37 CFR each sheet. 	correction filed <u>21</u> er's Amendment / Co	April 2003, which homment or in the Of	nas been approved ffice action of Paper	No
9. DEPOSIT OF and/or INFORMATION about the deposit attached Examiner's comment regarding REQUIREMENT FOR The state of t	osit of BIOLOGIC THE DEPOSIT OF	AL MATERIAL mi BIOLOGICAL MATI	ust be submitted. ERIAL.	Note the
Attachment(s) 1 Notice of References Cited (PTO-892) 3 Notice of Draftperson's Patent Drawing Review (PTO-948) 5 Information Disclosure Statements (PTO-1449), Paper No. 7 Examiner's Comment Regarding Requirement for Deposit of Biological Material	4□ 6□ 8⊠] Interview Summar] Examiner's Amend	Patent Application (y (PTO-413), Paper dment/Comment nent of Reasons for	No

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DETAILED ACTION

1. Amendment B filed on 4/21/03 has been fully considered and made of record in Paper No. 7.

Allowable Subject Matter

2. The following is a statement of reasons for the indication of allowance subject matter: the prior art of record does not teach or suggest the combination of a first semiconductor die with a plurality of bond pads and at least one redistribution bond pad circuit thereon, wherein the plurality of bond pads are electrically connected to integrated circuitry of the first semiconductor die and the redistribution bond pad circuit is electrically isolated from the integrated circuitry. A second semiconductor die having a plurality of bond pads, wherein active surface of the second die faces the active surface of the first die. An electrical connector extending between at least one of the plurality of bond pads on the second die and at least one redistribution bond pad of the plurality of redistribution bond pads on the first die in claims 1 and 22.

A first semiconductor die with a plurality of bond pads and a second semiconductor die with a plurality of bond pads, wherein the active surface of the second die faces the active surface of the first die. The second die having a peripheral edge extending laterally beyond at least one corresponding peripheral edge of the plurality of peripheral edges of the first die. A third semiconductor die disposed directly below the second die, wherein the third die has a plurality of bond pads and at least one redistribution bond pad circuit thereon. The plurality of bond pads are electrically

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connected to integrated circuitry of the third semiconductor die and the redistribution bond pad circuit is independent from the integrated circuitry. An electrical connector extending between at least one of the plurality of bond pads on the second die to contact an area of a substrate adjacent to the peripheral edge of the first die in claim 98.

Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (703) 306-9143. The fax phone number for the Group is (703) 308-772 or 7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the group receptionist whose telephone number is (703) 308-7956.

AC/June 29, 2003

Alonzo Chambliss Patent Examiner Art Unit 2827